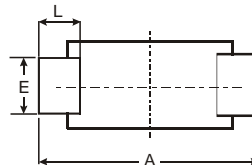
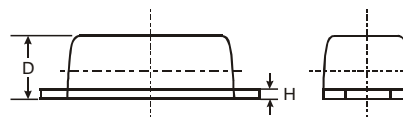
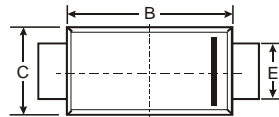
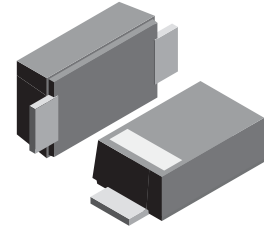


VOLTAGE RANGE: 20 - 100V
CURRENT: 2.0 A

Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O



SMAF			
Dim	Min	Max	Typ
A	4.75	4.85	4.80
B	3.68	3.72	3.70
C	2.57	2.63	2.60
D	0.097	1.03	1.00
E	1.38	1.42	1.40
H	0.13	0.17	0.15
L	0.63	0.67	0.65
All Dimensions in mm			

Mechanical Data

- Case: SMAF, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0018 ounce, 0.064 grams



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SK22AF	SK23AF	SK24AF	SK25AF	SK26AF	SK28AF	SK29AF	SK210AF	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	40	50	60	80	90	100	V
Working Peak Reverse Voltage	V _{RWM}									
DC Blocking Voltage	V _R									
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @T _L = 105°C	b	2.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50								A
Forward Voltage @I _F = 2.0A	V _{FM}	0.55				0.70		0.85		V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}					0.5				mA
						20				
Typical Thermal Resistance (Note 1)	R _{θJL} R _{θJA}					17				°C/W
						75				
Operating Temperature Range	T _J	-65 to +125								°C
Storage Temperature Range	T _{STG}	-65 to +150								°C

Note: 1. Mounted on P.C. Board with 8.0mm² copper pad area.



RATINGS AND CHARACTERISTIC CURVES SK22AF THRU SK210AF

FIG. 1- FORWARD CURRENT DERATING CURVE

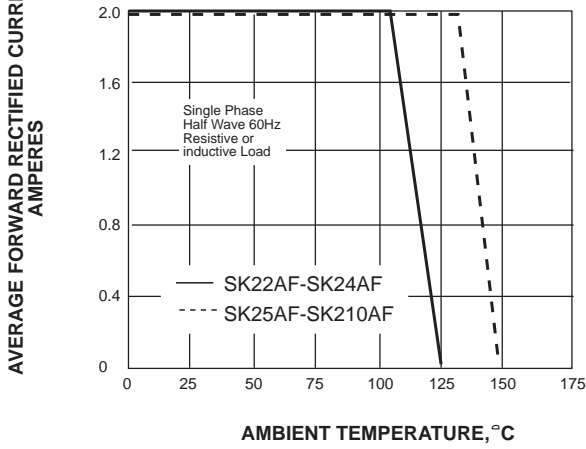


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

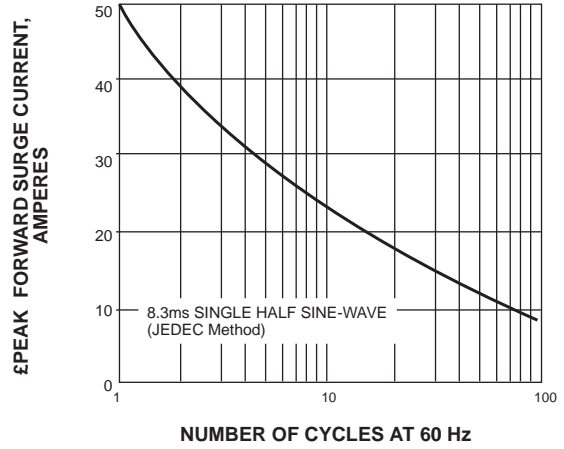


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

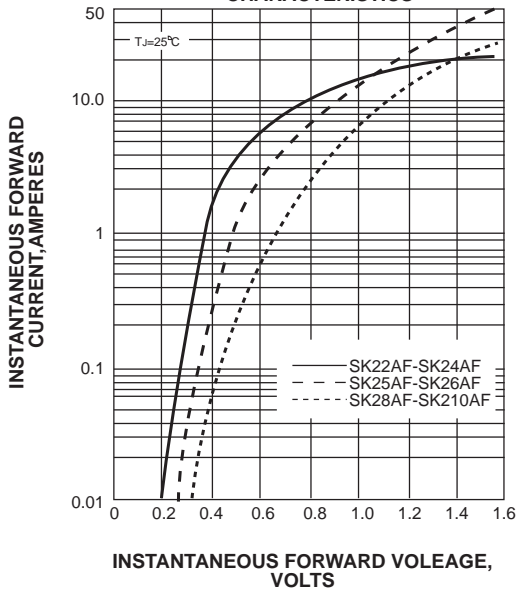


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

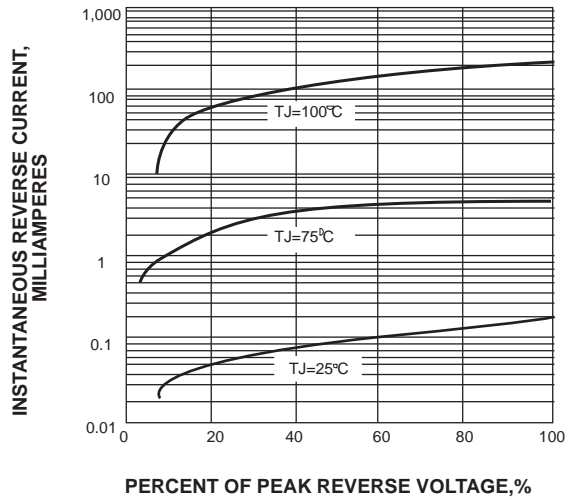


FIG. 5-TYPICAL JUNCTION CAPACITANCE

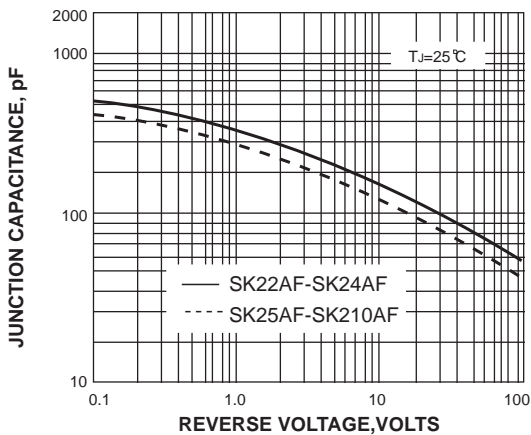


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

